CMOS MSI

Quad R–S Latches

The MC14043B and MC14044B quad R-S latches are constructed with MOS P-Channel and N-Channel enhancement mode devices in a single monolithic structure. Each latch has an independent Q output and set and reset inputs. The Q outputs are gated through three-state buffers having a common enable input. The outputs are enabled with a logical "1" or high on the enable input; a logical "0" or low disconnects the latch from the Q outputs, resulting in an open circuit at the Q outputs.

Features

- Double Diode Input Protection
- Three-State Outputs with Common Enable
- Outputs Capable of Driving Two Low-power TTL Loads or One Low-Power Schottky TTL Load Over the Rated Temperature Range
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- These Devices are Pb-Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V _{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	–0.5 to V _{DD} + 0.5	V
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P _D	Power Dissipation, per Package (Note 1)	500	mW
T _A	Ambient Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
ΤL	Lead Temperature (8-Second Soldering)	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, Vin and Vout should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



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MARKING DIAGRAMS



D SUFFIX CASE 751B	140xxBG <u> o</u> AWLYWW UUUUUUUU 1
SOEIAJ-16 F SUFFIX CASE 966	16
= Specific Dev = Assembly Lo = Wafer Lot = Year - Work Week	
	CASE 751B SOEIAJ-16 F SUFFIX CASE 966 = Specific Dev = Assembly Lu = Wafer Lot

Pb–Free Indicator

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

PIN ASSIGNMENT

1010140430							
Q3 [1•	16] V _{DD}				
Q0 [2	15] R3				
R0 [3	14] S3				
S0 [4	13	D NC				
E	5	12] S2				
S1 [6	11] R2				
R1 [7	10] Q2				
v _{ss} [8	9] Q1				

	MC14044B							
Q3 [1•	16	D V _{DD}					
NC [2	15] <u>53</u>					
<u>50</u> [3	14] R3					
R0 [4	13] Q0					
ΕC	5	12] R2					
R1 [6	11] <u>52</u>					
<u>51</u> [7	10] Q2					
V _{SS} [8	9] Q1					

NC = NO CONNECTION







S	R	Е	Q
Х	х	0	High Impedance
0	0	1	0
0	1	1	1
1	0	1	0
1	1	1	No Change
X =	Do	on't	Care

ELECTRICAL CHARACTERISTICS	(Voltages Referenced to V _{SS})
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			- 5	5°C		25°C		125	5°C	
Characteristic	Symbol	V _{DD} Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Мах	Unit
Output Voltage "0" Leve V _{in} = V _{DD} or 0	I V _{OL}	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
"1" Leve $V_{in} = 0$ or V_{DD}	I V _{OH}	5.0 10 15	4.95 9.95 14.95		4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95		Vdc
$\label{eq:VO} \begin{array}{l} \mbox{Input Voltage} & "0" \mbox{Leve} \\ (V_O = 4.5 \mbox{ or } 0.5 \mbox{ Vdc}) \\ (V_O = 9.0 \mbox{ or } 1.0 \mbox{ Vdc}) \\ (V_O = 13.5 \mbox{ or } 1.5 \mbox{ Vdc}) \end{array}$	I V _{IL}	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
"1" Leve $(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	I V _{IH}	5.0 10 15	3.5 7.0 11	_ _ _	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11	_ _ _	Vdc
$\begin{array}{l} \mbox{Output Drive Current} \\ (V_{OH} = 2.5 \ Vdc) \\ (V_{OH} = 4.6 \ Vdc) \\ (V_{OH} = 9.5 \ Vdc) \\ (V_{OH} = 13.5 \ Vdc) \end{array}$	I _{OH}	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	- - -	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	- - -	- 1.7 - 0.36 - 0.9 - 2.4	- - -	mAdc
$\begin{array}{l} (V_{OL} = 0.4 \ Vdc) & Sin \\ (V_{OL} = 0.5 \ Vdc) \\ (V_{OL} = 1.5 \ Vdc) \end{array}$	(I _{OL}	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mAdc
Input Current	l _{in}	15	-	±0.1	-	±0.00001	±0.1	-	±1.0	μAdc
Input Capacitance (V _{in} = 0)	C _{in}	-	-	-	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package)	I _{DD}	5.0 10 15	_ _ _	1.0 2.0 4.0		0.002 0.004 0.006	1.0 2.0 4.0	_ _ _	30 60 120	μAdc
Total Supply Current (Notes 3 & 4) (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs all buffers switching)	Ι _Τ	5.0 10 15		<u>.</u>	I _T = (1	.58 μΑ/kHz) .15 μΑ/kHz) .73 μΑ/kHz)	f + I _{DD}	·	<u>.</u>	μAdc
Three-State Output Leakage Current	I _{TL}	15	-	± 0.1	-	± 0.0001	± 0.1	-	± 3.0	μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

 $I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$

where: I_T is in μA (per package), C_L in pF, V = ($V_{DD} - V_{SS}$) in volts, f in kHz is input frequency, and k = 0.004.

Characteristic	Symbol	V _{DD} Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise Time t _{TLH} = (1.35 ns/pF) C _L + 32.5 ns	t _{TLH}	5.0	-	100	200	ns
$t_{TLH} = (0.60 \text{ ns/pF}) \text{ C}_{L} + 20 \text{ ns}$ $t_{TLH} = (0.40 \text{ ns/pF}) \text{ C}_{L} + 20 \text{ ns}$		10 15		50 40	100 80	
Output Fall Time t _{THL} = (1.35 ns/pF) C _L + 32.5 ns t _{THL} = (0.60 ns/pF) C _L + 20 ns t _{THL} = (0.40 ns/pF) C _L + 20 ns	t _{THL}	5.0 10 15		100 50 40	200 100 80	ns
Propagation Delay Time $t_{PLH} = (0.90 \text{ ns/pF}) \text{ C}_{L} + 130 \text{ ns}$ $t_{PLH} = (0.36 \text{ ns/pF}) \text{ C}_{L} + 57 \text{ ns}$ $t_{PLH} = (0.26 \text{ ns/pF}) \text{ C}_{L} + 47 \text{ ns}$	^t PLH	5.0 10 15		175 75 60	350 175 120	ns
t _{PHL} = (0.90 ns/pF) C _L + 130 ns t _{PHL} = (0.90 ns/pF) C _L + 57 ns t _{PHL} = (0.26 ns/pF) C _L + 47 ns	t _{PHL}	5.0 10 15		175 75 60	350 175 120	ns
Set, Set Pulse Width	t _W	5.0 10 15	200 100 70	80 40 30	- - -	ns
Reset, Reset Pulse Width	t _W	5.0 10 15	200 100 70	80 40 30	- - -	ns
Three-State Enable/Disable Delay	t _{PLZ} , t _{PHZ} , t _{PZL} , t _{PZH}	5.0 10 15		150 80 55	300 160 110	ns

SWITCHING CHARACTERISTICS (Note 5) ($C_1 = 50 \text{ pF}$, $T_A = 25^{\circ}C$)

The formulas given are for the typical characteristics only at 25°C.
 Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.



AC WAVEFORMS

THREE-STATE ENABLE/DISABLE DELAYS

Set, Reset, Enable, and Switch Conditions for 3-State Tests

					MC14043B		MC14044B	
Test	Enable	S1	S2	Q	S	R	S	R
t _{PZH}	~	Open	Closed	А	V_{DD}	V_{SS}	V_{SS}	V _{DD}
t _{PZL}	7	Closed	Open	В	V_{SS}	V_{DD}	V_{DD}	V_{SS}
t _{PHZ}	~	Open	Closed	А	V_{DD}	V_{SS}	V_{SS}	V _{DD}
t _{PLZ}	~	Closed	Open	В	V_{SS}	V_{DD}	V_{DD}	V_{SS}





ORDERING INFORMATION

Device	Package	Shipping [†]
MC14043BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14043BDG	SOIC-16	48 Units / Rail
NLV14043BDG*	(Pb-Free)	
MC14043BDR2G	SOIC-16	2500 Units / Tape & Reel
NLV14043BDR2G*	(Pb-Free)	
MC14043BFELG	SOEIAJ-16	2000 Units / Tape & Reel
MC14044BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14044BDG	SOIC-16	48 Units / Rail
NLV14044BDG*	(Pb-Free)	
MC14044BDR2G	SOIC-16	2500 Units / Tape & Reel
NLV14044BDR2G*	(Pb-Free)	

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable.

PACKAGE DIMENSIONS

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 **ISSUE T**



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL. 1.
- 2.
- З.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH. 4.
- 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIM	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
κ	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
М	0 °	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

SOEIAJ-16 **F SUFFIX** PLASTIC EIAJ SOIC PACKAGE CASE 966-01 **ISSUE A**









NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI 1.
 - Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 2.
 - 3.
 - 2. CONTROLLING DIMENSION, MILLING FER. 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15
- (0.006) PER SIDE. 4. TERMINAL NUMBERS ARE SHOWN FOR
- IEHMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE O.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENDER DE MEMBERS ARE DANNED TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.45 (0.019) TO BE 0.46 (0.018).

	MILLIN	IETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
Μ	0 °	10 °	0 °	10 °
Q ₁	0.70	0.90	0.028	0.035
Z		0.78		0.031

PACKAGE DIMENSIONS



DIMENSIONING AND TOLERANCING PER ANSI

Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.

DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
Κ	0.10	0.25	0.004	0.009
М	0 °	7°	0 °	7°
Р	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019



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